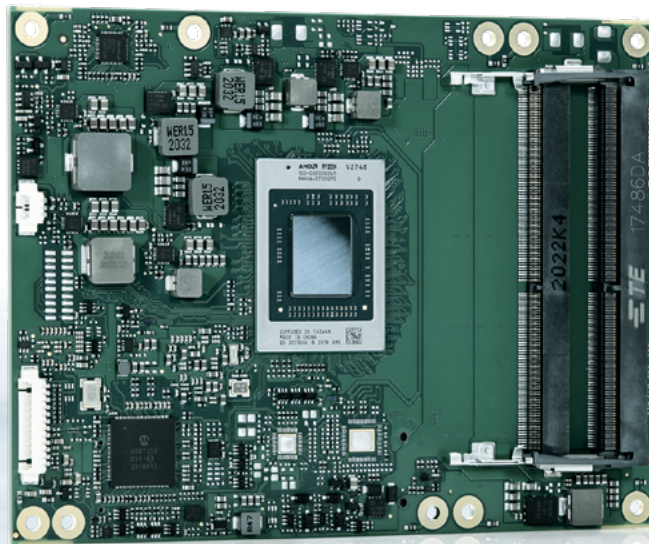


# COMe-bV26

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## COM Express® Basic V2000 with AMD Embedded V-Series high-performance “Zen2” CPU

- ▶ Up to 64 GByte DDR4 memory (2x 32 GByte dual-channel DDR4 SO-DIMM)
- ▶ Up to 8 PCIe lanes (4x PCIe 3.0 (up to 8 GT/s) 4x PCIe 2.0 (up to 5 GT/s))
- ▶ Optional up to 1 TByte NVMe SSD onboard

POSSIBILITIES START HERE

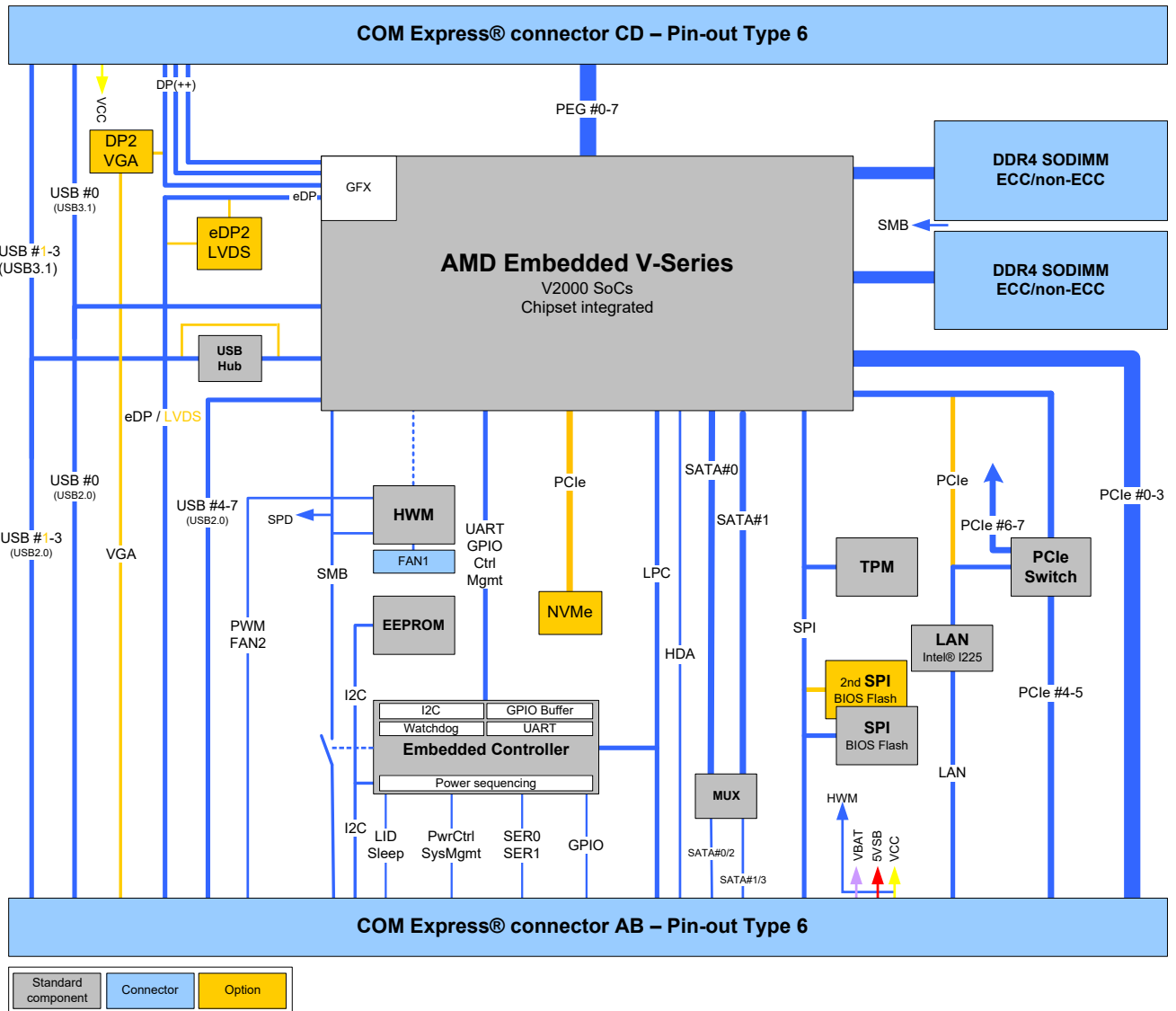
## ► TECHNICAL INFORMATION

COMPLIANCE	COM Express® basic pin-out type 6
DIMENSIONS (H x W x D)	95 x 125 mm
CPU	AMD Embedded V-Series V2000 SoCs: AMD V2748, 8x 2.9 GHz, 35-54 W AMD V2718, 8x 1.7 GHz, 12-25 W AMD V2546, 6x 3.0 GHz, 35-54 W AMD V2516, 6x2.1 GHz, 12-25 W
CHIPSET	Integrated in SoC
MAIN MEMORY	2x DDR4 SO DIMM (up to 32 GByte per channel)
GRAPHICS CONTROLLER	AMD "Vega7" Core GPU with up to 7 Compute Units
ETHERNET CONTROLLER	Intel® i225
STORAGE	2x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS®	4x PCIe 3.0 (up to 8 GT/s) 4x PCIe 2.0 (up to 5 GT/s) via PCIe switch 1x PEG x8
DISPLAY	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	4x USB 3.1 + 8x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	Default Audio support Baseboard Audio with external HAD Codec on carrier
POWER MANAGEMENT	OS ACPI PM support for critical shutdown
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
BIOS	AMI UEFI (incl. support for AMI tools)
OPERATING SYSTEM	Windows®10, Linux (Yocto based)
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)

## ► CPU VARIANTS

CPU	V2748	V2718	V2546	V2516
CORES	8	8	6	6
FREQUENCY BASE/TURBO	2.9/4.25 GHz	1.7/4.15 GHz	3/3.95 GHz	2.10/3.95 GHz
TDP	35/54 W	12/25 W	35/54 W	12/25 W
CACHE	4 MByte	4 MByte	3 MByte	3 MByte

► BLOCK DIAGRAM



► VARIANTS

PART NO.	CPU	PCH	MEM. DOWN	SO-DIMM	FLASH	OP. TEMPERATURE
38036-0000-29-8 *	V2748	integrated	-	non-ECC/ECC		0 °C - 60 °C
38036-0000-17-8 *	V2718	integrated	-	non-ECC/ECC		0 °C - 60 °C
38036-0000-30-6 *	V2546	integrated	-	non-ECC/ECC		0 °C - 60 °C
38036-0000-21-6 *	V2516	integrated	-	non-ECC/ECC		0 °C - 60 °C

\* Qualified for E1 temperature range (-25 °C to +75 °C) and available project based only

## ► CARRIER

ARTICLE	PART NO.	DESCRIPTION
COM Express® REFERENCE CARRIER -i TYPE 6	38115-0000-00-x	Thin-mITX carrier with 5 mm COMe connector
COM Express® EVAL CARRIER2 TYPE 6	38116-0000-00-5	ATX carrier with 5 mm COMe connector

## ► COOLING

ARTICLE	PART NO.	DESCRIPTION
HSP COMe-bV26 CU-CORE THREADED	38036-0000-99-0	Heatspreader for COMe-bV26, Cu-core, threaded mounting holes
HSP COMe-bV26 CU-CORE THROUGH	38036-0000-99-1	Heatspreader for COMe-bV26, Cu-core, through mounting holes

## ► MEMORY

PART NO.	MIN. SPEC.	SIZE	ECC	OP. TEMPERATURE
97020-0432-BV26	DDR4-3200	4 GByte	no	0 °C - 60 °C
97020-0832-BV26	DDR4-3200	8 GByte	no	0 °C - 60 °C
97020-1632-BV26	DDR4-3200	16 GByte	no	0 °C - 60 °C
97020-3232-BV26	DDR4-3200	32 GByte	no	0 °C - 60 °C
97030-0432-BV26	DDR4-3200	4 GByte	yes	0 °C - 60 °C
97030-0832-BV26	DDR4-3200	8 GByte	yes	0 °C - 60 °C
97030-1632-BV26	DDR4-3200	16 GByte	yes	0 °C - 60 °C
97030-3232-BV26	DDR4-3200	32 GByte	yes	0 °C - 60 °C
97021-0432-BV26*	DDR4-3200	4 GByte	no	-40 °C - 85 °C
97021-0832-BV26*	DDR4-3200	8 GByte	no	-40 °C - 85 °C
97021-1632-BV26*	DDR4-3200	16 GByte	no	-40 °C - 85 °C
97021-3232-BV26*	DDR4-3200	32 GByte	no	-40 °C - 85 °C

\* Corresponding memory modules in case of project based E1 temperature range variants

## ► GLOBAL HEADQUARTERS

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